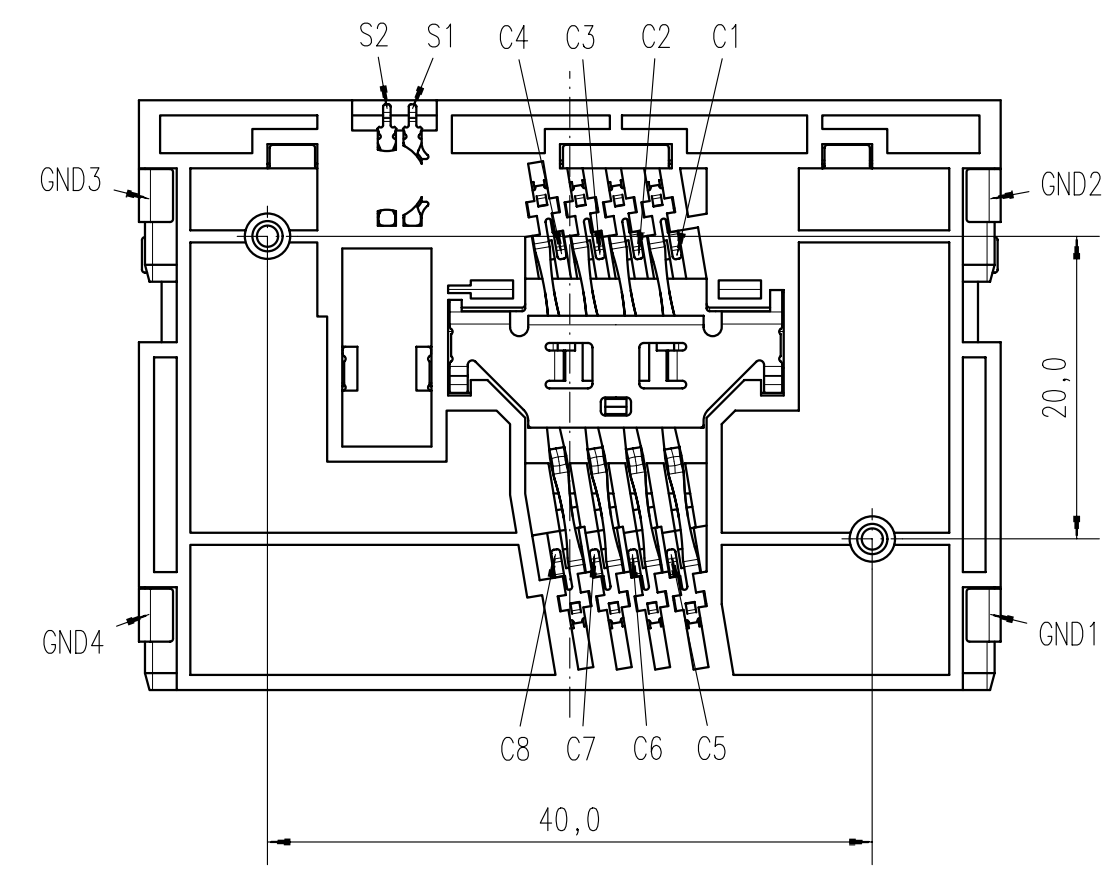
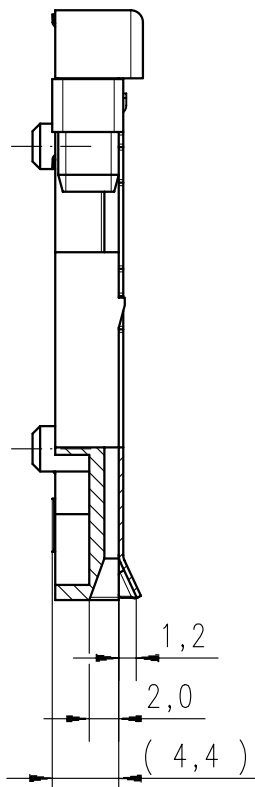
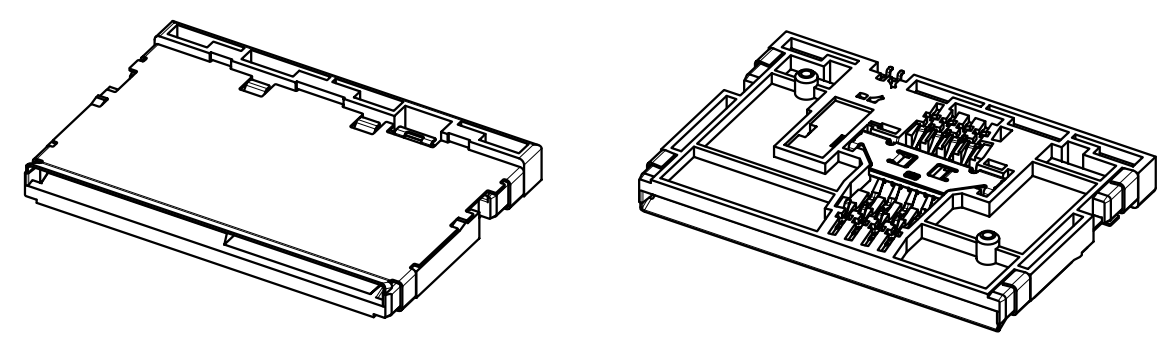
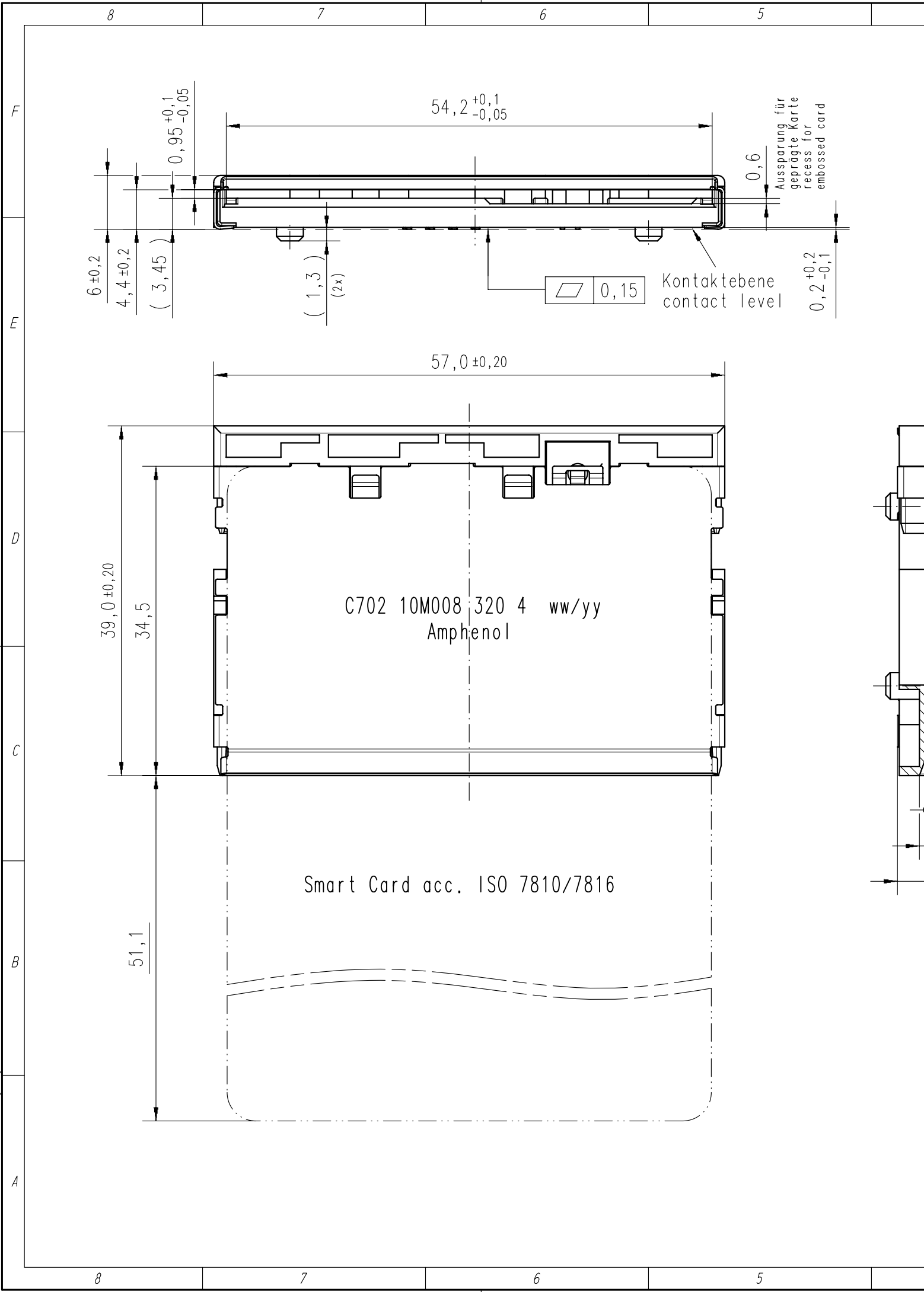


Copying of this document and giving it to others and the use or communication of the contents thereof, are forbidden without express authority. Offenders are liable to the payment of damages. All rights are reserved in the event of the grant of a patent or the registration of the utility model or design.

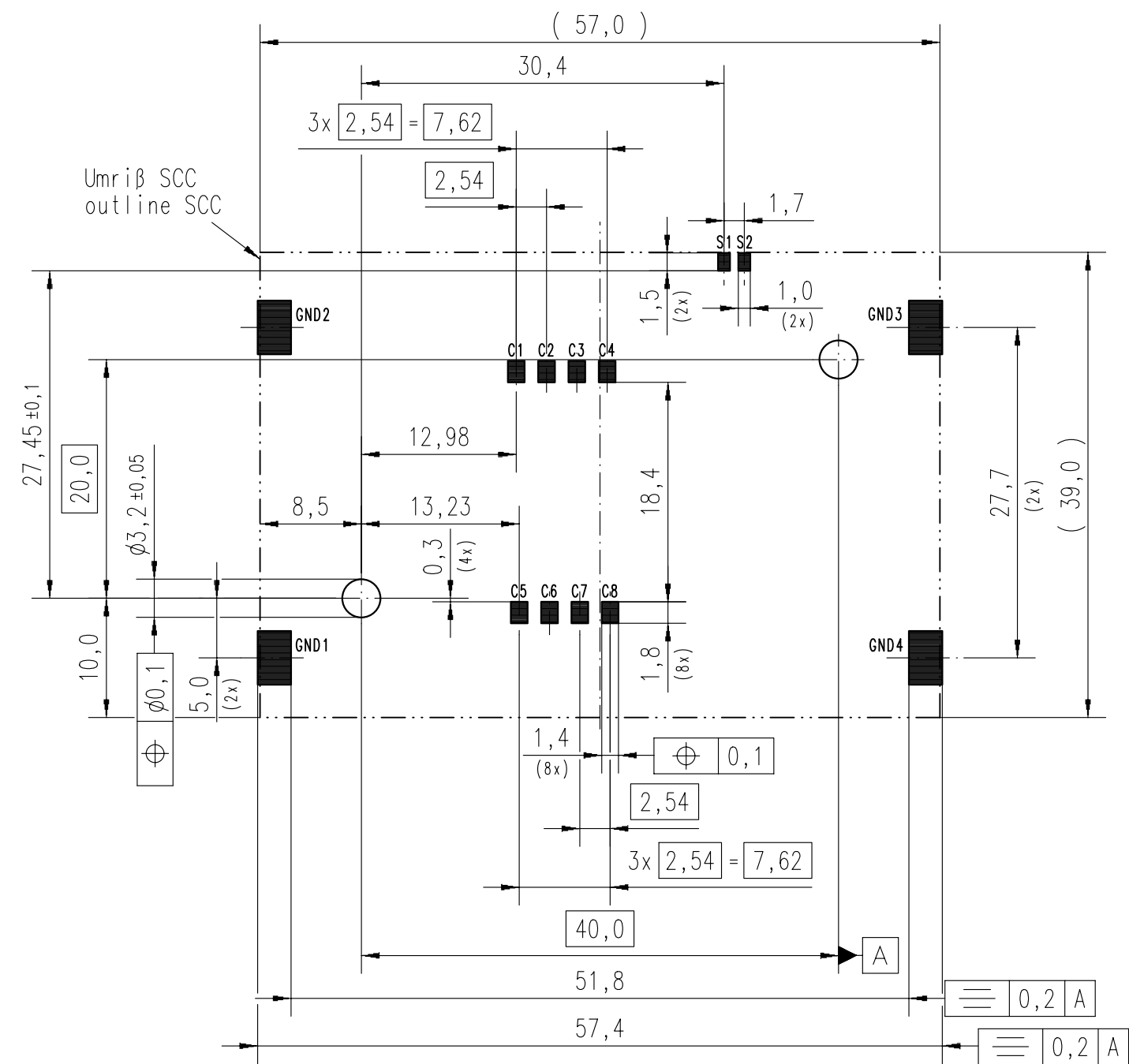


Spezifikation und Leiterplattenlayout siehe Seite 2  
 Specification and PCB layout see page 2

Masse (errechnet)/Calc WF: 11,8 <sup>9</sup>		Zul. Abw./Tolerances:		Maßstab/Scale 2:1		A3	
Prüfmaß/Testdimension		ISO 2768-mH		DIN/ISO 13715		CUSTOMER DRAWING	
Teileindex Partindexnumber 02 <sup>03</sup>		11 Datum/Date		Name		Smart Card Connector push-pull, landing contacts	
		Gez. 28.07.		Bertsch			
		Gepr.					
		Checked					
03	201200737	10.12.12	ToI.	Amphenol-Tuchel Electronics GmbH		M	C702 10M008 320 4
02	201200200	15.03.12	ToI.				
01	201000417	29.07.11	Ber.				
Index	Änderung/Description	Datum/Date	Name	Ers. f./Replacement for:		Blatt/Sheet 1	
						2 Bl.	

Copying of this document and giving it to others and the use or communication of the contents thereof, are forbidden without express authority. Offenders are liable to the payment of damages. All rights are reserved in the event of the grant of a patent or the registration of the utility model or design.

vorgeschlagenes Leiterplattenlayout (Bestückungsseite)  
proposed PCB layout (component side)



empfohlene Lotpastendicke: 0,18 mm  
No-Clean Lötpaste verwenden, Bauteil ist nicht waschbar  
recommended solder paste thickness: 0,18 mm  
No-Clean solder paste recommended, part is not washable

Kennwerte  
Characteristics

DESIGN  
type: push-pull, landing contacts  
normally open switch  
with positioning studs

GENERAL CHARACTERISTICS  
number of contacts: 8 contacts  
switch: normally open (no card inserted)  
card type: according to ISO 7810 / 7816  
card thickness: 0,76 ±0,08 mm  
termination: SMT

MATERIALS AND PLATING  
insulator: LCP, black  
contact plating: Au over Ni

CLIMATIC CHARACTERISTICS  
operating temperature: -25 °C to +70 °C  
storage temperature: -40 °C to +85 °C  
soldering process: reflow soldering

ELECTRICAL CHARACTERISTICS  
contact resistance: < 60 mΩ (data contacts)  
< 1 Ω (switch)  
insulation resistance: >10<sup>9</sup> Ω  
high voltage resistance: 500 V AC for 1 minute  
rated voltage: <15 V DC  
rated current: <0,5 A

MECHANICAL CHARACTERISTICS  
card insertion force: <12 N  
⊗ card holding force: >2 N  
mechanical lifetime: 500.000 mating cycles  
(without corrosion stress)

PACKAGING ⊗ 22 parts per tray  
21 trays per carton

ausführliche Spezifikation siehe N 50 702 0053  
full specification see N 50 702 0053

Weitergabe sowie Vervielfältigung dieser Unterlage, Verwertung und Mitteilung ihres Inhalts nicht gestattet, soweit nicht ausdrücklich zugestanden. Zuwiderhandlungen verpflichten zu Schadenersatz. Alle Rechte für den Fall der Patenterteilung oder Gebrauchsmuster-Eintragung vorbehalten.

Masse (errechnet)/Calc WT: 11,8 g		Zul. Abw./Tolerances:		Maßstab/Scale 2:1		A3	
Prüfmaß/Testdimension		ISO 2768-mH		DIN/ISO 13715		CUSTOMER DRAWING	
Teileindex Partindexnumber 02 <sup>⊗</sup>		11 Datum/Date		Name		Smart Card Connector	
		Gez. 28.07.		Bertsch		push-pull, landing contacts	
		Drawn					
		Gepr.					
		Checked					
03	201200737	10.12.12	ToI.	Amphenol-Tuchel Electronics GmbH		Blatt/Sheet 2	
02	201200200	15.03.12	ToI.			M C702 10M008 320 4	
01	201000417	29.07.11	Ber.			2 Bl.	
Index	Änderung/Description	Datum/Date	Name	Ers. f./Replacement for:			